



**AT&S**

# **CONSISTENCY IN** **CHANGE**



**22nd Credit Suisse Asian Technology Conference**  
Investor and Analyst Presentation

06 - 07 September, 2021

# DRIVING SUSTAINABILITY

High level of social, ecological and economic responsibility

## 2025

**80%**  
renewable energies

**30%** share of women in  
leadership positions

**Vitality Index**  
**>20%**

**Strengthening partnerships**  
with suppliers

## Achievements<sup>1</sup>

Share of renewable energies  
of **45%<sup>2</sup>**

Share of women in leadership  
positions of **20%**

Vitality index  
of **21%**

**100%** of main suppliers  
signed our Code of Conduct

<sup>1</sup> As of 31.03.2021 | <sup>2</sup> Including big hydro power

## Rated by



# LEADING PROVIDER OF HIGH-END PCBs & IC SUBSTRATES

## Well positioned for the future

### Unique market position

- Broad product portfolio to serve all growth markets
- Long-standing customer relationships with technology and market leaders
- Technology innovator due to continuous R&D efforts
- Quality benchmark with outstanding process know-how, productivity and efficiency

### Growth oriented strategy

- Megatrend-driven markets with attractive growth potential
- Address growth opportunities with incremental investments
- Constant outperformance of the PCB & substrates market

€1.2 bn

revenue  
FY 20/21

~€3 bn

revenue FY 25/26

# 5

ABF substrates  
producer  
worldwide

Top 3

in FY 25/26

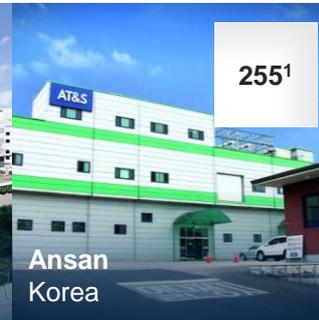
# 2

high-end PCB  
producer  
worldwide

ONE

of the leading  
high-end PCB  
producers  
worldwide

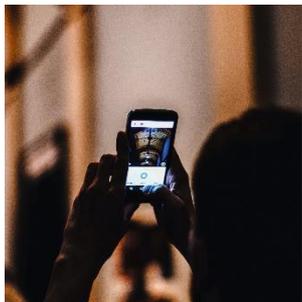
# GLOBAL FOOTPRINT



● AT&S plant    ● AT&S sales support office    📍 AT&S Headquarters

<sup>1</sup> Staff, Average, FTE, FY 20/21; 80 employees in other locations

# MARKET SEGMENTS & PRODUCT APPLICATIONS



**Mobile devices**

- Smartphones
- Wearables
- Notebooks & tablets
- Consumer electronics (action cameras and drones)



**IC substrates**

- High-performance computers
- Servers
- Client PCs
- Cloud & Edge computing
- 5G base stations
- Networking & gaming



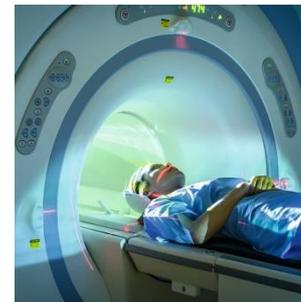
**Automotive**

- ADAS
- Autonomous driving (radar, camera, V-to-X communication)
- Power supply for motor systems



**Industrial**

- Smart building, grid, lighting, manufacturing, transportation & retail
- Telecom infrastructure
- Power management
- Robots



**Medical**

- Diagnostics and imaging systems
- Therapy application (pacemakers, hearing aids, drug delivery ...)
- Patient monitoring

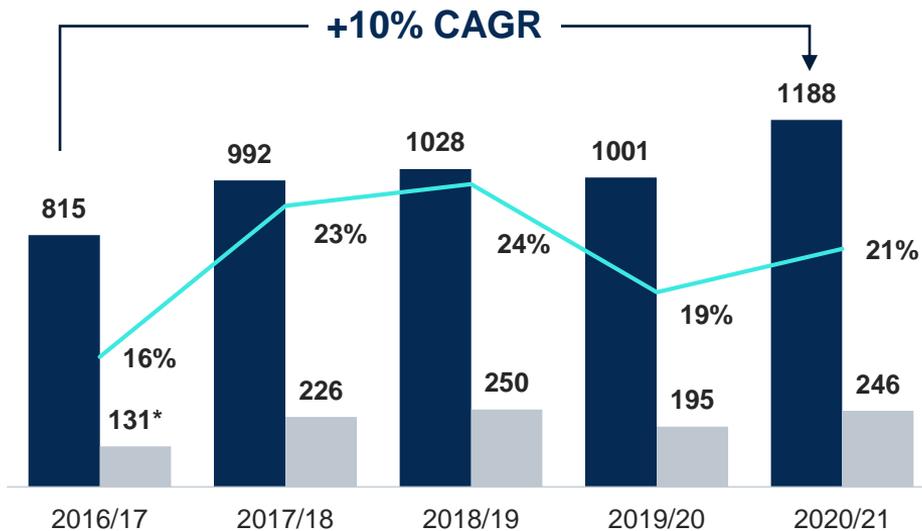
## Segment Mobile Devices & Substrates

## Segment Automotive, Industrial, Medical

# KEY FACTS

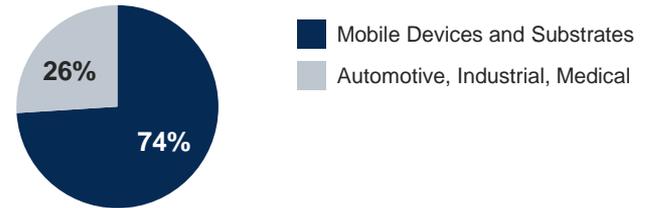
## Outperformed the market in the last years

In € mn



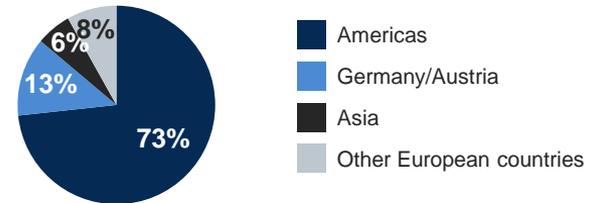
■ Revenue   ■ EBITDA   — EBITDA margin   \*Including ramp-up effects for plants in China

### Revenue split by segment: FY 20/21



### Revenue split by customer: FY 20/21

Based on customer's headquarters



# AT&S OUTPERFORMS PCB & IC SUBSTRATES\* MARKET GROWTH

in US\$ bn



	CY 2020	YoY	CY 2021	CAGR	CY 2026
Automotive	6.2	+19.4%	7.4	+4.1%	9.1
Aviation	2.8	+7.6%	3.0	+2.4%	3.4
Industrial	2.5	+12.4%	2.8	+2.5%	3.2
Medical	1.3	+9.1%	1.4	+2.5%	1.6
IC Substrates*	7.7	+25.0%	9.6	+8.7%	14.5
Communication	18.0	+10.9%	19.9	+5.4%	25.9
Computer	16.4	+14.3%	18.8	+1.8%	20.5
Consumer	8.0	+13.1%	9.0	+2.4%	10.1

Confirmed position as  
**#2 producer**  
for high end PCBs

AT&S will continue to outperform the  
market with an annual growth of  
**>20% until 2026**

Source: Prismark 05-06/2021  
\* only containing high-end IC substrates

# STRATEGIC BUSINESS DRIVERS



# GAME CHANGERS ARE DRIVING OUR BUSINESS

New technologies and systems bring a significant data volume increase



**5G**

**Big Data**

**Artificial Intelligence**

**Internet of Things**

# INCREASING DATA VOLUMES REQUIRE NEW DESIGN SOLUTIONS AND BETTER PERFORMANCE

Existing technologies cannot meet future requirements

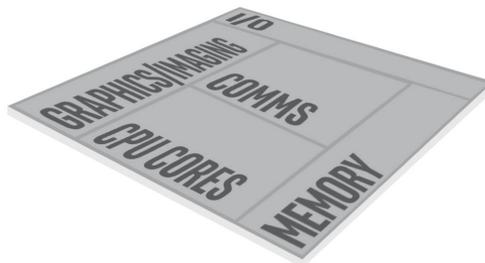


Increased data volumes need to be transmitted, stored and processed

Instead of using monolithic designs, various chip elements are integrated as one device

## MONOLITHIC CHIP

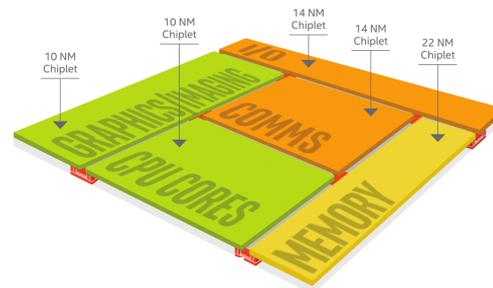
A singular piece of silicon, constructed as a unit



Source: Intel

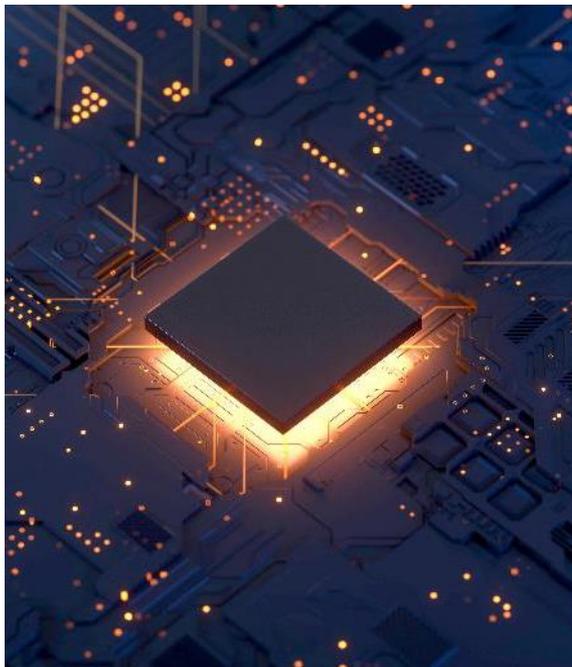
## CHIPLETS

A heterogeneous collection of “chiplets” integrated as one device



# **HIGH-PERFORMANCE PROCESSORS NEED HIGH-PERFORMANCE ABF SUBSTRATES**

## **Growing demand supports AT&S growth strategy**



Servers, networking, AI and gaming are driving the trend towards significantly bigger and more complex substrates

- Increased substrate size
- Increased layer count
- Increased interconnect density

**AT&S is significantly increasing capacities for highly complex substrates to support these technology developments**

# NEW MANUFACTURING SITE IN KULIM / MALAYSIA

## Additional capacities for IC substrates

**Future  
diversification  
of the  
customer  
portfolio**

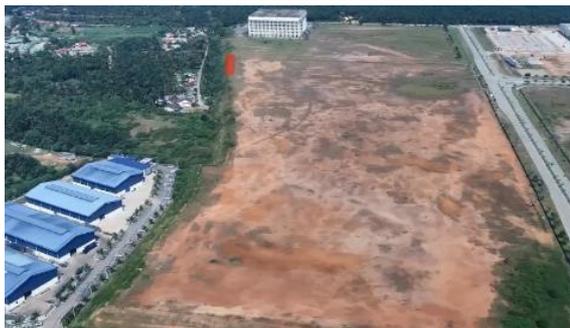
- Investment of up to € 1.7 billion in Kulim, Malaysia
  - ABF substrates for high-performance processors
  - Construction of new production complex between 2021 - 2026
  - Appr. 230,000 m<sup>2</sup> in size
- Collaboration with two leading manufacturers of high-performance-computing semiconductors
- Significant part of project financing is based on agreements with customers
- About half of the investment volume is to be provided by the customers' contributions to financing

# UPDATE ABF SUBSTRATES PROJECTS



## **CHONGQING III**

- First parts of the production equipment have already been qualified as well as be put into operation
- Process & equipment characterisation and certification earlier
- Full capacities available with the beginning of Q4 2023

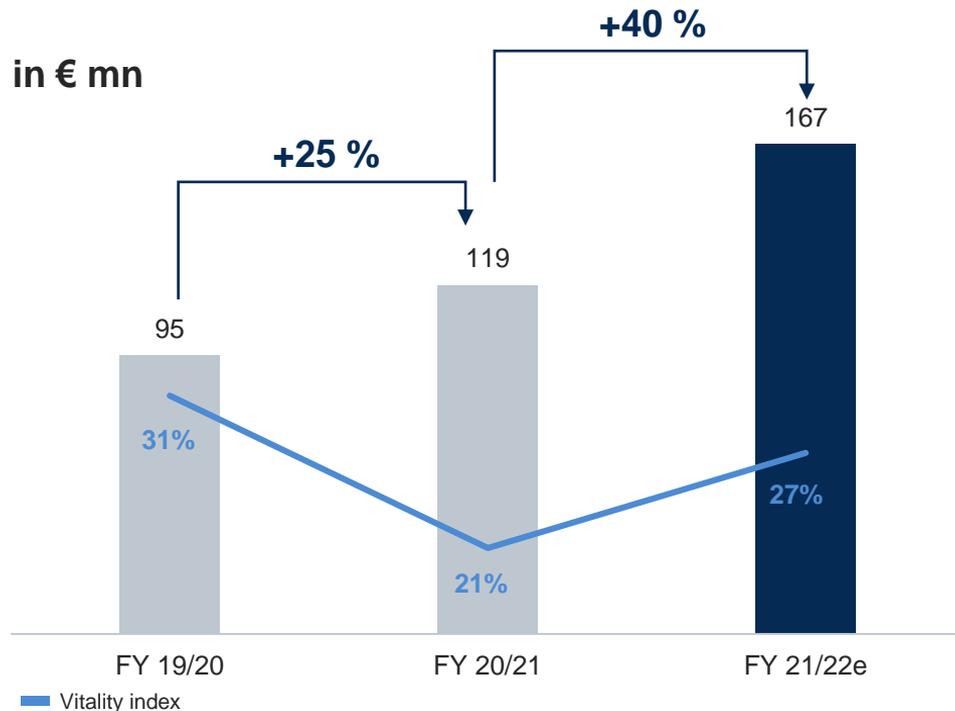


## **KULIM**

- Contract with customers signed and measures taken to start project
- Construction scheduled to start in the second half of CY 2021 and high volume production at the end of CY 2024

# STRONG COMMITMENT TO INNOVATION AND GROWTH

R&D investments – a key revenue and margin driver



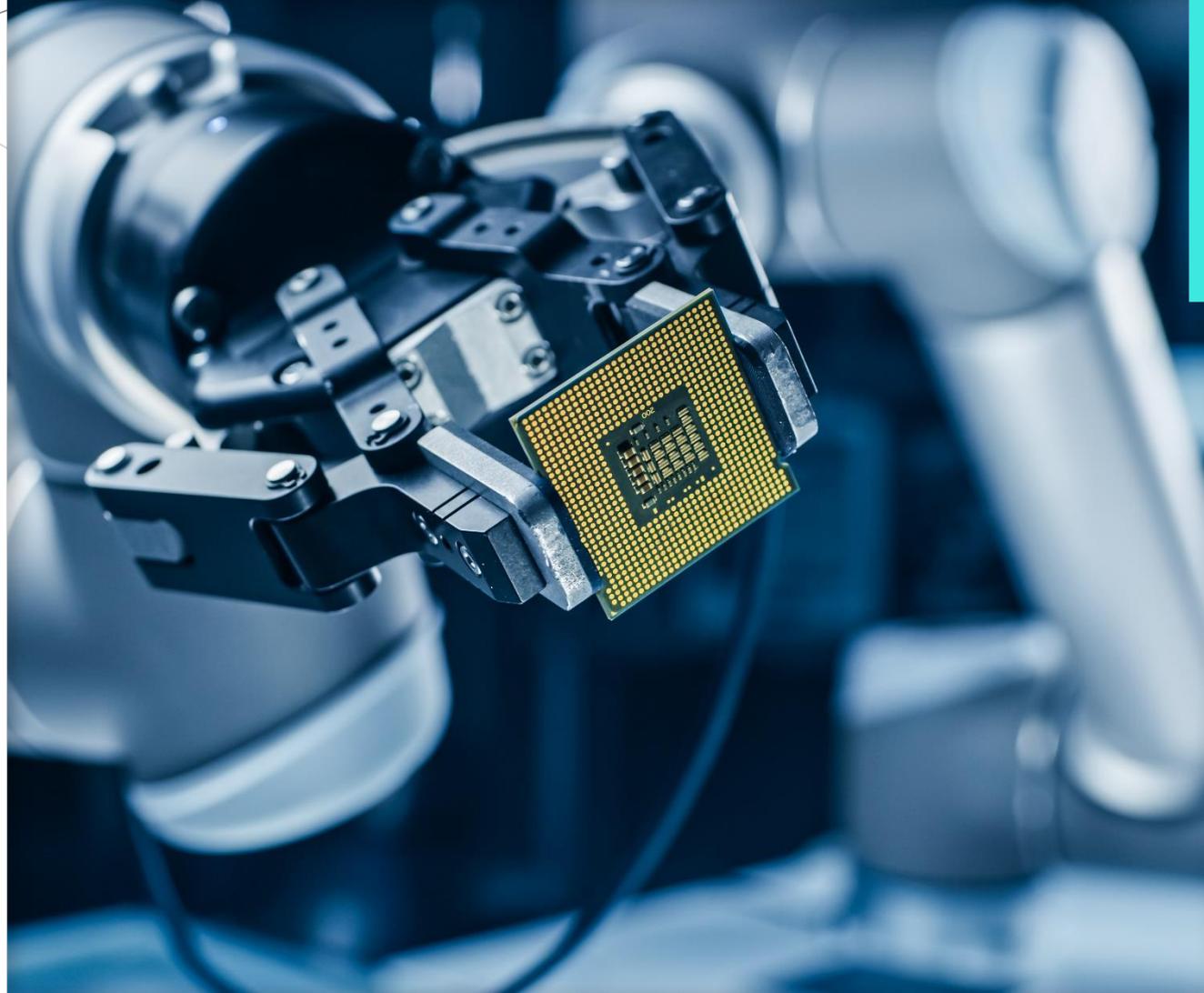
## Investments in R&D

a key part of our focused business strategy

Target

**Vitality index > 20%**

## RESULTS Q1 21/22



# KEY DEVELOPMENTS Q1 21/22

All business segments contributed to company growth

**Growth  
continued  
unabated**

- Strong revenue growth of +28%
  - Additional capacities and strong demand push ABF substrates business
  - PCBs for modules with further growth
  - Automotive recovery
  - Industrial with strong performance
- Strengthen the R&D activities to secure technology leadership
- Strong focus on preparing organisation for the future growth
- Capacity expansion projects fully on track

# Q1 21/22 RESULTS SUMMARY

## Revenue at historic high

Revenue **+28%**

**€ 318 mn**

- Negative FX effects of € 22 mn

EBITDA margin **-130 bps**

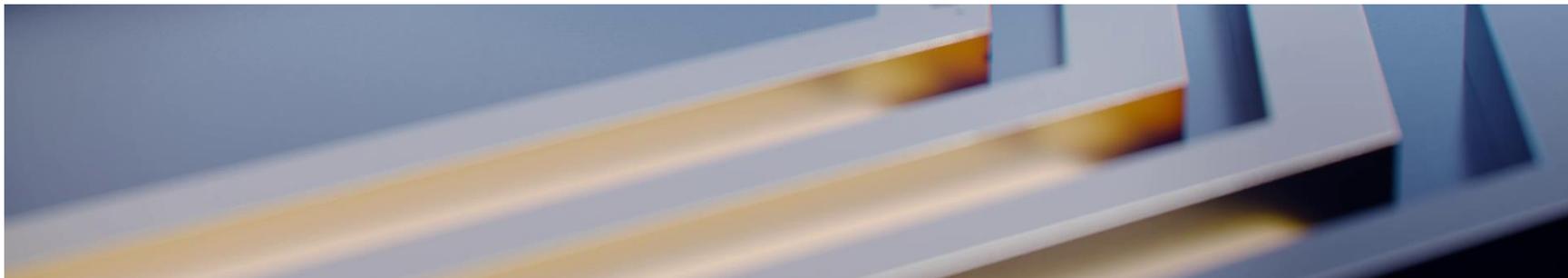
**14.6%**

- EBITDA margin burdened by negative FX effects of € 18 mn

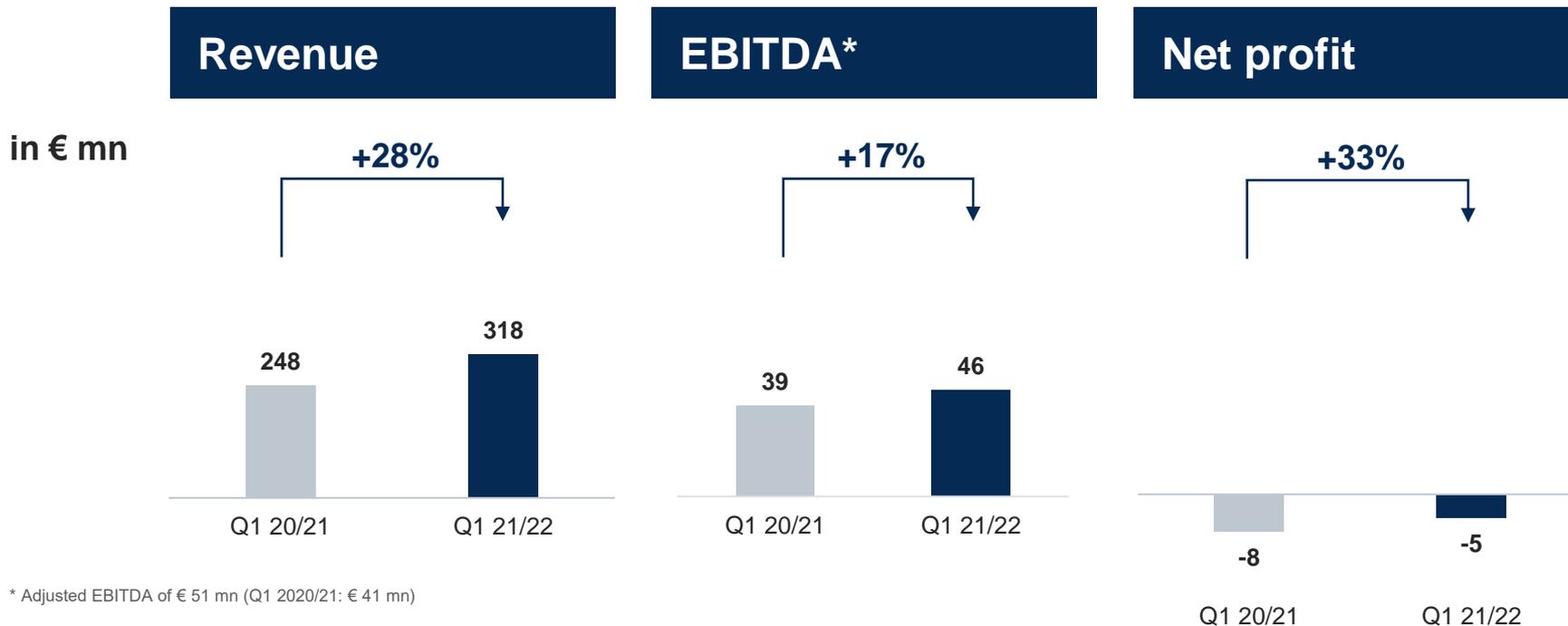
Adjusted EBITDA margin **-50 bps**

**16.0%**

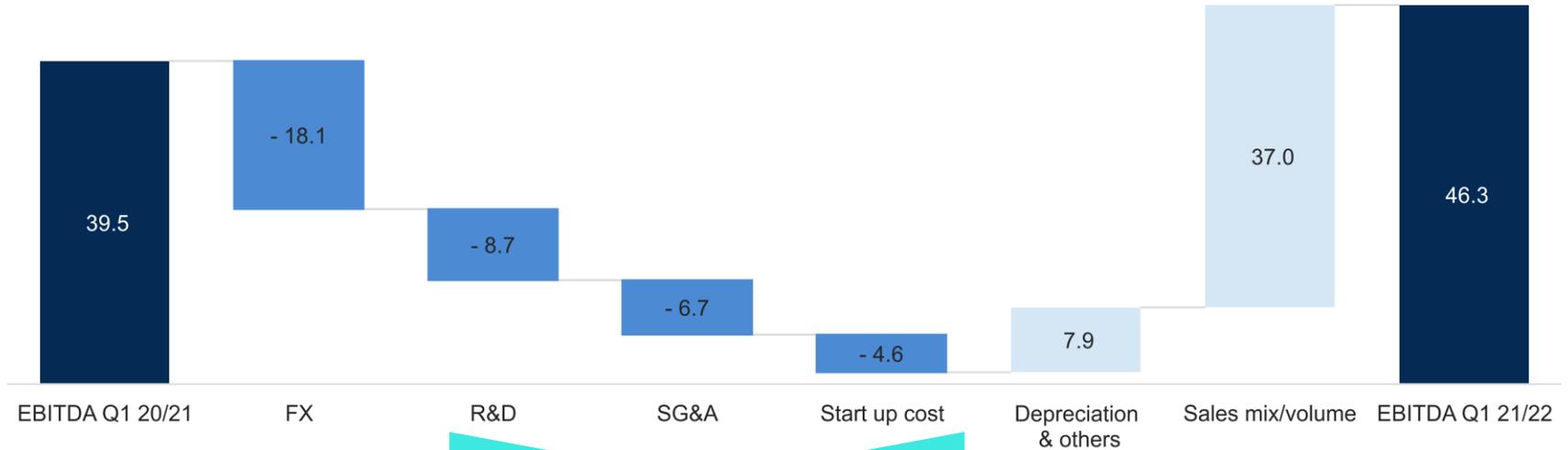
- Start-up costs for materials and wages of € 4.5 mn excluded



# Q1 21/22 RESULTS SUMMARY



# EBITDA BRIDGE Q1



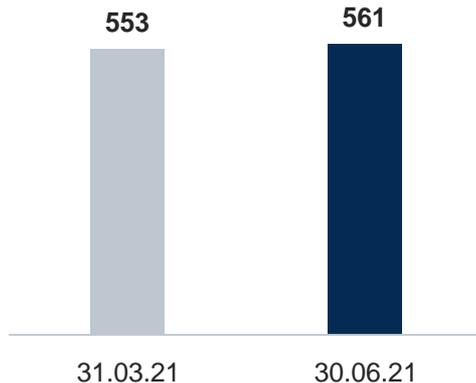
Investments to prepare  
for future growth

# Q1 21/22 FINANCIAL POSITION

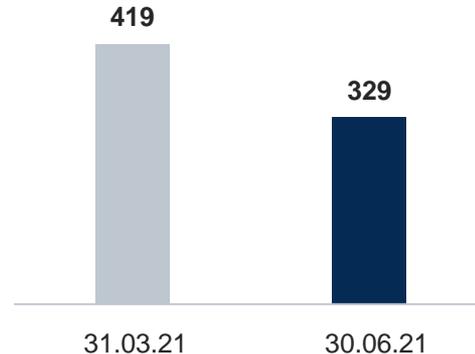
Solid financial structure for future growth

## Cash & cash equivalents

in € mn



## Unused credit lines



## Balancing capital allocation

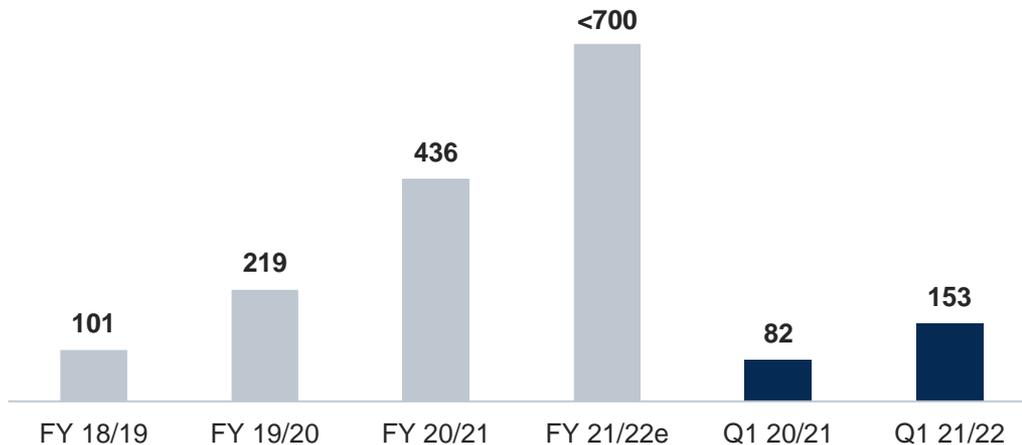
- Deploying capital with clear approach to invest in strategic growth markets

**Sound investment decisions to generate strong operating and free cash flow in the future.**

# NET CAPEX

Further investments mainly pushed by IC substrates

in € mn



## Capex outlook 2021/22

- **CAPEX guidance increased** from up to € 630 mn to up to € 700 mn
- CAPEX increase is mainly related to the new production site for IC substrates in Kulim
- CAPEX for strategic projects of up to € 450 mn plus € 80 mn due to timing variances
- Depending on market developments CAPEX for maintenance and tech upgrade of up to € 100 mn

# CURRENT YEAR GUIDANCE

## FY 21/22 – Revenue guidance increased

**Growth** Revenue growth of 17 – 19% (previous: 13 – 15%)

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**Profitability**

- Adjusted EBITDA margin of 21 – 23%
- Adjustment: Start-up effects of the Chongqing and Kulim projects with an amount of appr. € 50 mn

# MIDTERM GUIDANCE

## FY 25/26 – Considering the investment in Malaysia

<b>Growth</b>	Revenue appr. € 3 bn (CAGR +20%)
<b>Profitability</b>	<ul style="list-style-type: none"><li>▪ EBITDA margin of 27 – 32%</li><li>▪ ROCE of &gt;12% with ramp-up of production</li></ul>
<b>Others</b>	<ul style="list-style-type: none"><li>▪ Net debt/EBITDA: &lt;3 (can be temporarily exceeded)</li></ul>

# ANNEX



# MARKET PLAYERS IN THE HIGH-END SEGMENT

## HDI Technology<sup>1</sup>

1	Compeq
2	AT&S
3	Unimicron
4	Tripod
5	Zhen Ding
6	AKM Meadville
7	Meiko
8	TTM

## ABF Substrates<sup>2</sup>

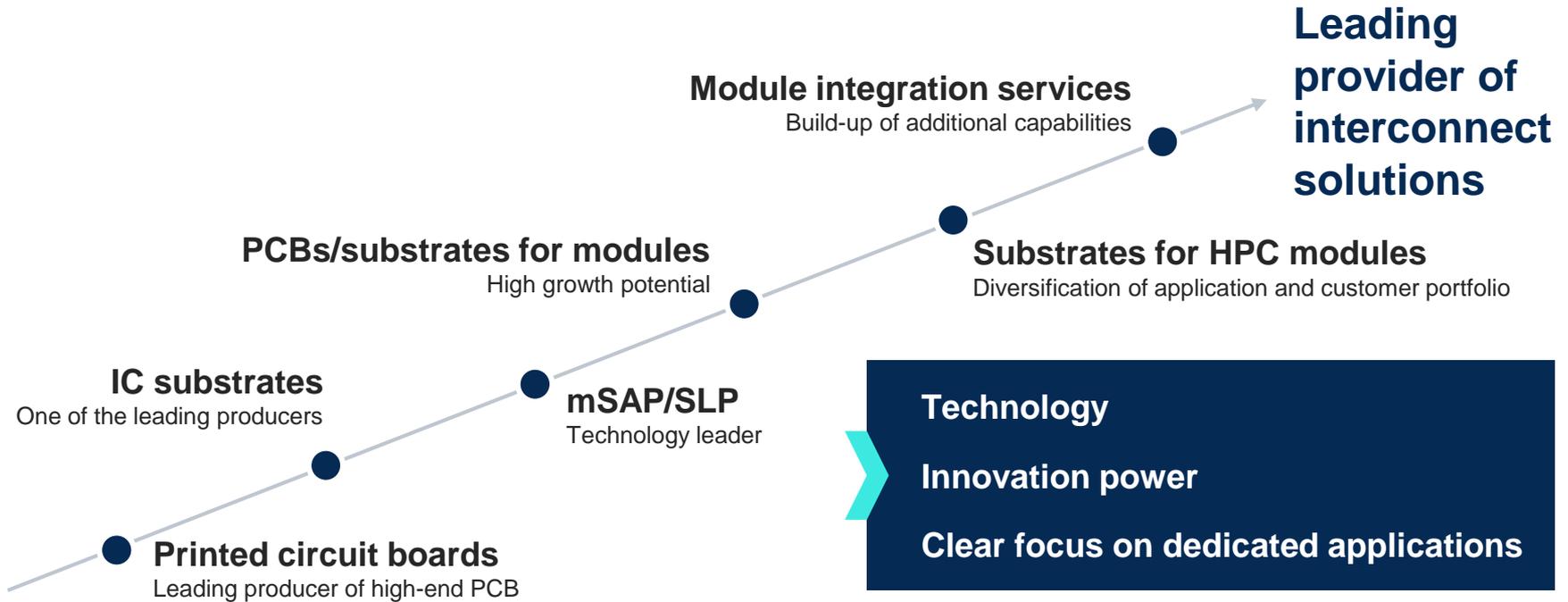
1	Ibiden
2	Unimicron
3	SEMCO
4	Shinko
5	AT&S
6	Kyocera
7	Nan Ya PCB
8	Kinsus

<sup>1</sup> for CY 2020 <sup>2</sup> for CY 2019

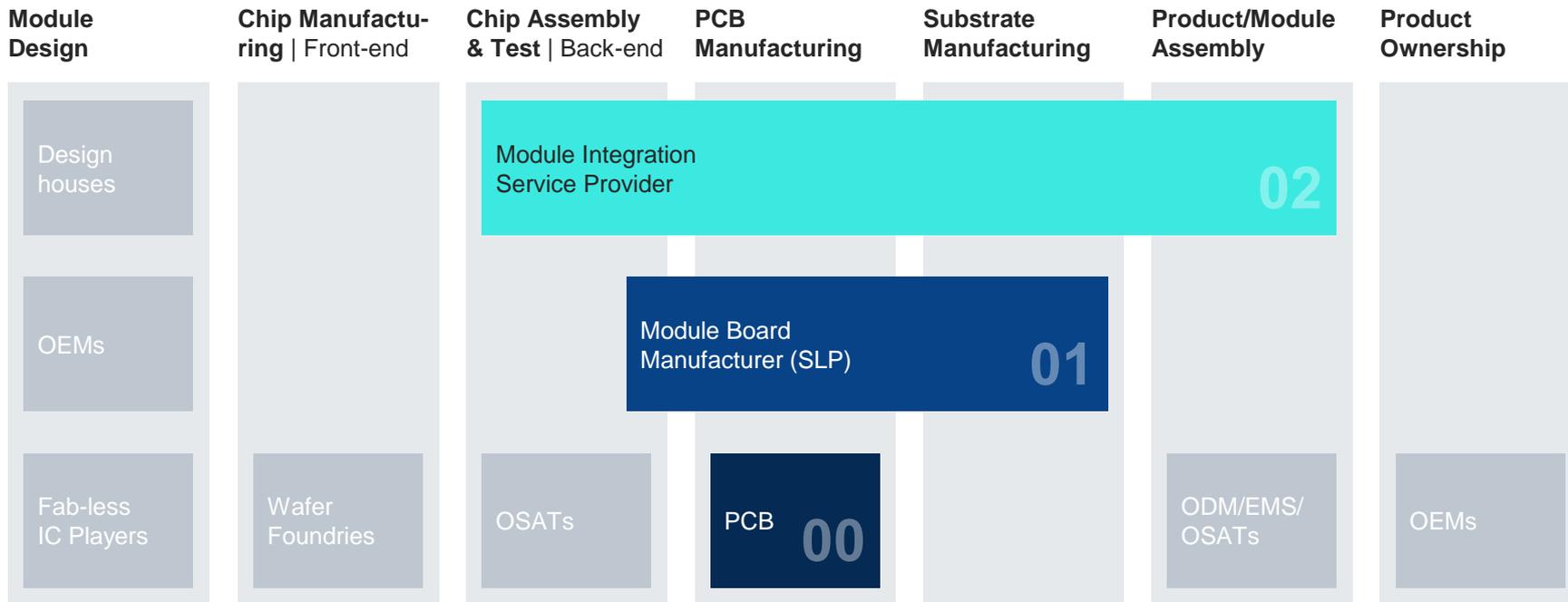
Source: Prismark, JMS, AT&S assessment

# MORE THAN AT&S

Broadening the service range and opening up of new business opportunities



# AT&S SOLUTIONS FOR THE ELECTRONICS INDUSTRY



# AT&S – STOCK PROFILE

## Listing

Vienna Stock Exchange,  
Prime Standard

## Indices

ATX, Vönix,  
WBI

## Thomson Reuters (A)

ATSV.VI

## Bloomberg (A)

ATS:AV

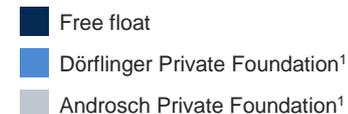
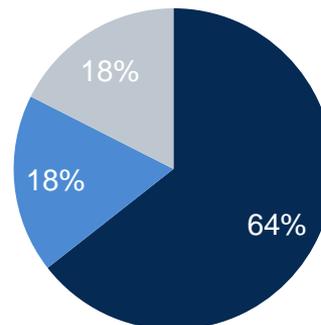
## # of shares outstanding

38.85 m

## Dividend for 20/21

€ 0.39 per share

## Shareholder structure



<sup>1</sup> Including direct and indirect holdings

# BALANCE SHEET

€ mn	31.03.2021	30.06.2021	Change in %
Total assets	2,390	<b>2,516</b>	+5%
Equity	802	<b>799</b>	-0.4%
Equity ratio	34%	<b>32%</b>	-180bps
Net debt	509	<b>638</b>	+26%

Ongoing expansion and technology upgrades main drivers for increase in total assets

Increase in total assets weighs on equity ratio

Higher CAPEX feeds into liquidity and drives up net debt

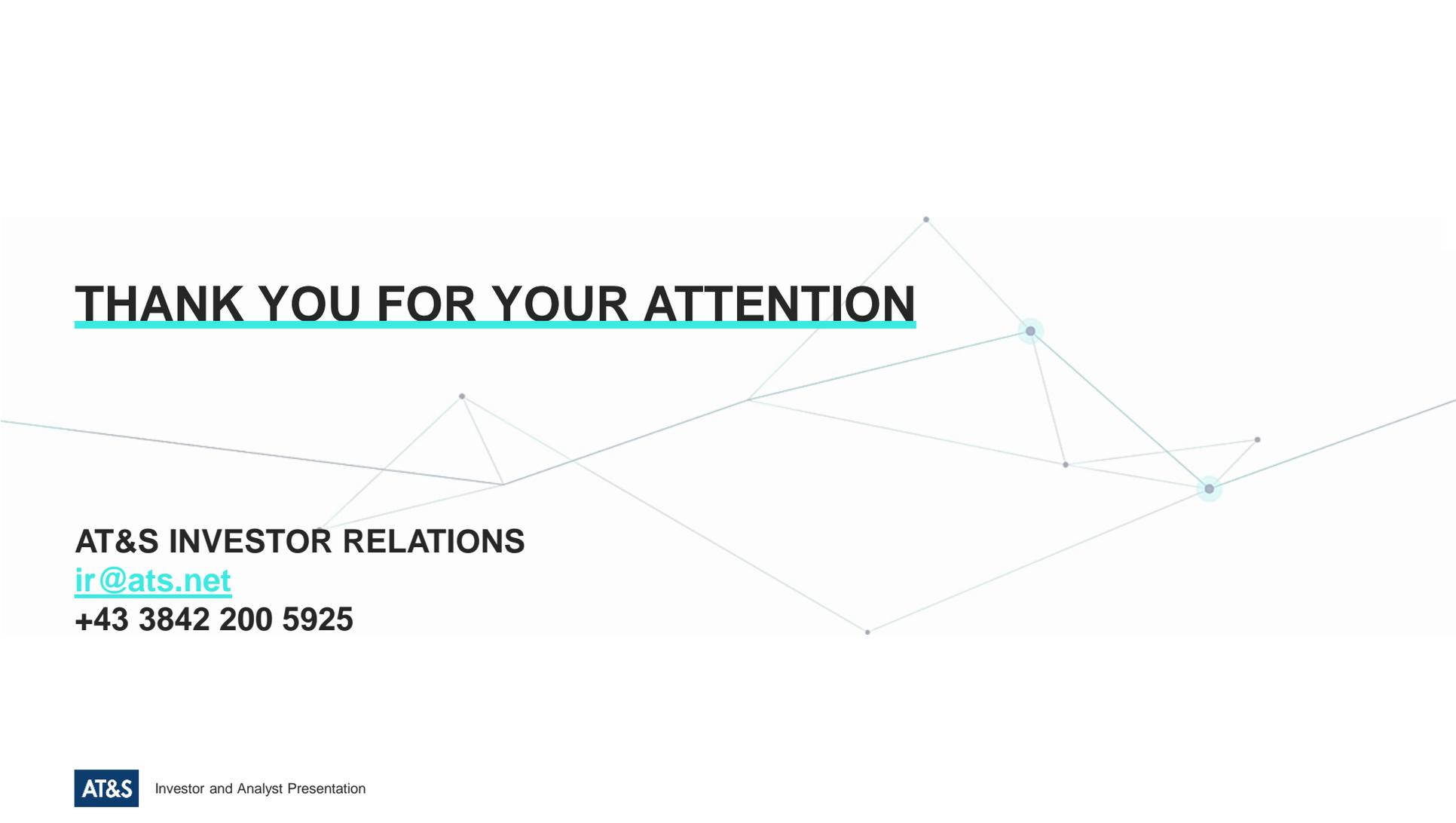
# CASH FLOW

Increase in Operating Cash flow driven by better result

€ mn	Q1 20/21	Q1 21/22	YoY Change in %
CF from operating activities	28	31	+8%
CF from investing activities	-171	-130	-24%
CF from financing activities	119	110	-8%
Operating free CF	-54	-123	>-100%

Higher CAPEX offset by lower investments in time deposits

Operating free CF mainly driven by higher CAPEX



**THANK YOU FOR YOUR ATTENTION**

**AT&S INVESTOR RELATIONS**

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